

FIELD EFFECT TRANSISTOR
SILICON N CHANNEL MOS TYPE (L²- π -MOS^{III})

2SK1347

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS.
RELAY DRIVE, MOTOR DRIVE AND DC-DC CONVERTER APPLICATIONS.

INDUSTRIAL APPLICATIONS

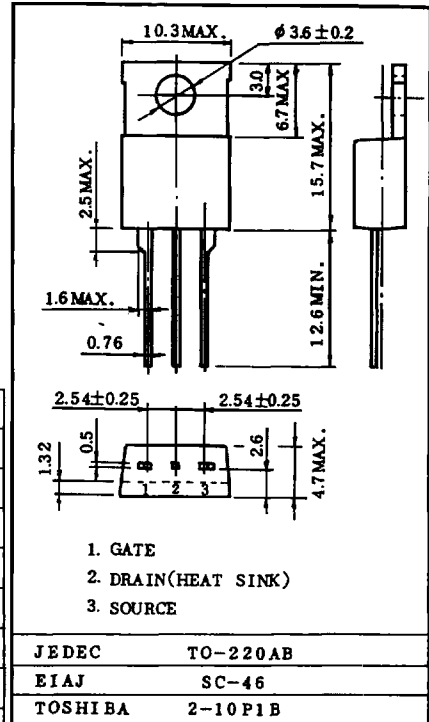
Unit in mm

FEATURES:

- 4-Volt Gate Drive
- Low Drain-Source ON Resistance : $R_{DS(ON)}=0.068\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 11S$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100\mu A$ (Max.) @ $V_{DS} = 100V$
- Enhancement-Mode : $V_{th} = 0.8 \sim 2.0V$ @ $V_{DS} = 10V, I_D = 1mA$

MAXIMUM RATINGS (Ta = 25 °C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	100	V
Drain-Gate Voltage (RGS=20k Ω)		V_{DGR}	100	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current	DC	I_D	20	A
	Pulse	I_{DP}	80	A
Drain Power Dissipation (Tc=25°C)		PD	75	W
Channel Temperature		Tch	150	°C
Storage Temperature Range		Tstg	-55~150	°C



Weight : 2.0g

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Impedance, Channel to Case	$R_{th(ch-c)}$	1.67	°C/W
Thermal Impedance, Channel To Ambient	$R_{th(ch-a)}$	83.3	°C/W

2SK1347

ELECTRICAL CHARACTERISTICS (Ta=25 °C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I _{GSS}	V _{GS} = ±20V, V _{DS} =0V	—	—	±100	nA
Drain Cut-off Current		I _{DSS}	V _{DS} =100V, V _{GS} =0V	—	—	100	μA
Drain-Source Breakdown Voltage		V(BR) _{DSS}	I _D =10mA, V _{GS} =0V	100	—	—	V
Gate Threshold Voltage		V _{th}	V _{DS} =10V, I _D =1mA	0.8	—	2.0	V
Drain-Source ON Resistance		R _{DS(ON)}	V _{GS} = 4V, I _D =5A	—	0.10	0.15	Ω
			V _{GS} =10V, I _D =10A	—	0.068	0.085	
Forward Transfer Admittance		Y _{fs}	V _{DS} =10V, I _D =10A	7	11	—	S
Input Capacitance		C _{iss}	V _{DS} =10V, V _{GS} =0V, f=1MHz	—	1050	1600	pF
Reverse Transfer Capacitance		C _{rss}		—	160	300	
Output Capacitance		C _{oss}		—	620	900	
Switching Time	Rise Time	t _r	<p> V_{GS} 10V V_{GS} 0V $I_D=10A$ V_{OUT} $R_L=5\Omega$ $V_{IN}: t_r < 5ns, \text{Duty} \leq 1\%, t_w=10\mu s$ $V_{DD} \approx 50V$ </p>	—	11	25	ns
	Turn-on Time	t _{on}		—	26	50	
	Fall Time	t _f		—	14	40	
	Turn-off Time	t _{off}		—	78	160	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q _g	V _{DD} ≈ 80V, V _{GS} =10V, I _D =20A	—	36	80	nC
Gate-Source Charge		Q _{gs}		—	23	—	
Gate-Drain(" Miller")Charge		Q _{gd}		—	13	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS(Ta=25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I _{DR}	---	—	—	20	A
Pulse Drain Reverse Current	I _{DRP}	---	—	—	80	A
Diode Forward Voltage	V _{DSF}	I _{DR} ≈ 20A, V _{GS} =0V	—	-1.0	-1.7	V
Reverse Recovery Time	t _{rr}	I _{DR} ≈ 20A, V _{GS} =0V	—	280	—	ns
Reverse Recovered Charge	Q _{rr}	dI _{DR} /dt = 50A/μs	—	0.7	—	μC